

September 2000



FQP6N80

800V N-Channel MOSFET

General Description

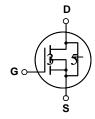
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

Features

- 5.8A, 800V, $R_{DS(on)}$ = 1.95 Ω @V_{GS} = 10 V Low gate charge (typical 31 nC)
- Low Crss (typical 14 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP6N80	Units	
V _{DSS}	Drain-Source Voltage		800	V	
I _D	Drain Current - Continuous (T _C = 25°C	;)	5.8	А	
	- Continuous (T _C = 100°C)		3.67	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	23.2	А	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	680	mJ	
I _{AR}	Avalanche Current	(Note 1)	5.8	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	15.8	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.0	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		158	W	
	- Derate above 25°C		1.27	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.79	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to	o 25°C		0.9		V/°C
I _{DSS}	- 0	V _{DS} = 800 V, V _{GS} = 0 V				10	μА
	Zero Gate Voltage Drain Current	V _{DS} = 640 V, T _C = 125°C				100	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics		,				
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10 V, I _D =2.9 A			1.5	1.95	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 2.9 A	(Note 4)		5.9		S
C _{iss} C _{oss}	Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			125 14	160 18	pF pF
C _{rss}	Reverse Transfer Capacitance				14	18	pF
Switchi	ng Characteristics						
t _{d(on)}	Turn-On Delay Time	V_{DD} = 400 V, I_{D} = 5.8 A, R_{G} = 25 Ω (Note 4, 5)			30	70	ns
t _r	Turn-On Rise Time				70	150	ns
t _{d(off)}	Turn-Off Delay Time				65	140	ns
t _f	Turn-Off Fall Time				45	100	ns
Qg	Total Gate Charge	$V_{DS} = 640 \text{ V}, I_{D} = 5.8 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)			31		nC
Q _{gs}	Gate-Source Charge				7.1		nC
Q_{gd}	Gate-Drain Charge				15		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings					
I _S	Maximum Continuous Drain-Source Diode Forward Current				5.8	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				23.2	Α	
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 5.8 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 5.8 \text{ A,}$ $dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)			650		ns
Q _{rr}	Reverse Recovery Charge				5.7		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 38mH, I_{AS} = 5.8A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 5.8A, di/dt \leq 200A/µs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

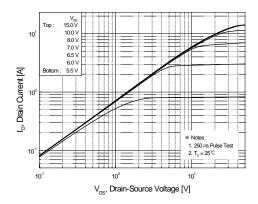


Figure 1. On-Region Characteristics

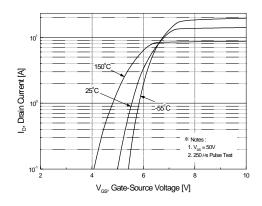


Figure 2. Transfer Characteristics

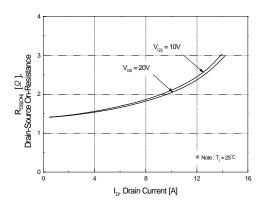


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

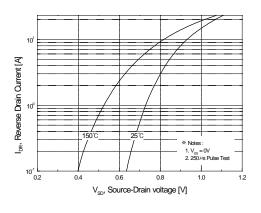


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

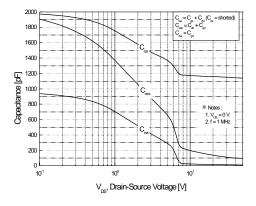


Figure 5. Capacitance Characteristics

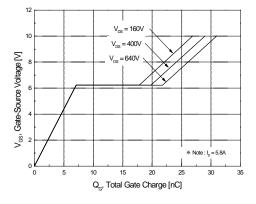


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

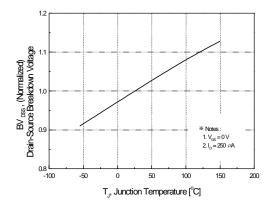
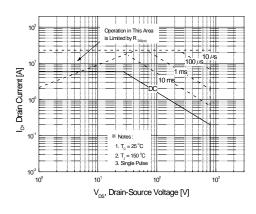


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



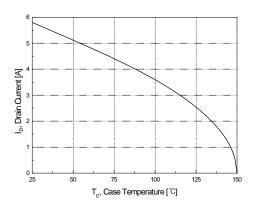


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

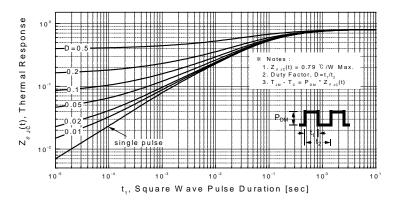
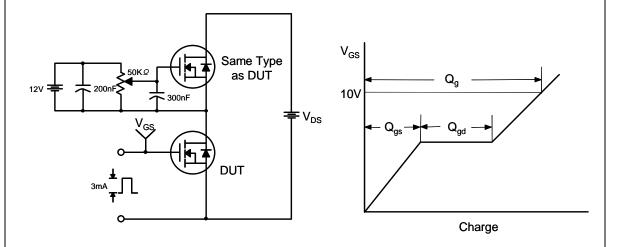


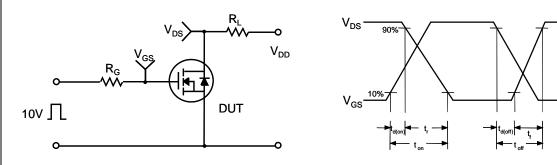
Figure 11. Transient Thermal Response Curve

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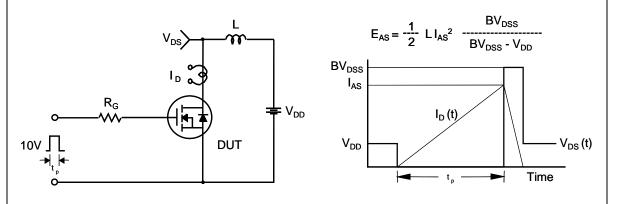
Gate Charge Test Circuit & Waveform



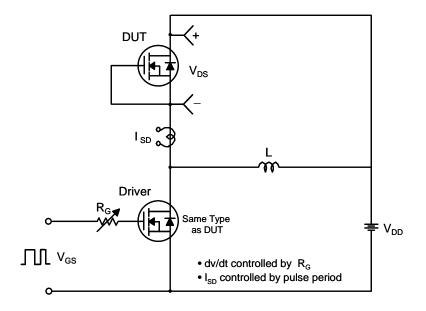
Resistive Switching Test Circuit & Waveforms

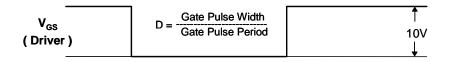


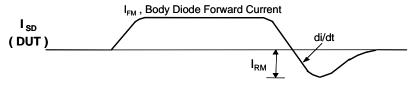
Unclamped Inductive Switching Test Circuit & Waveforms



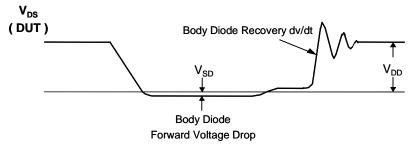
Peak Diode Recovery dv/dt Test Circuit & Waveforms

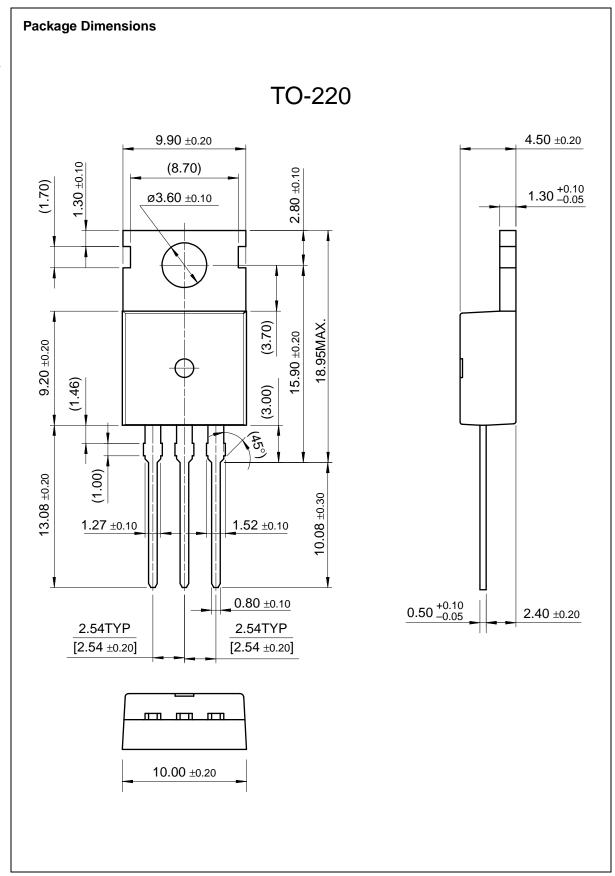






Body Diode Reverse Current





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